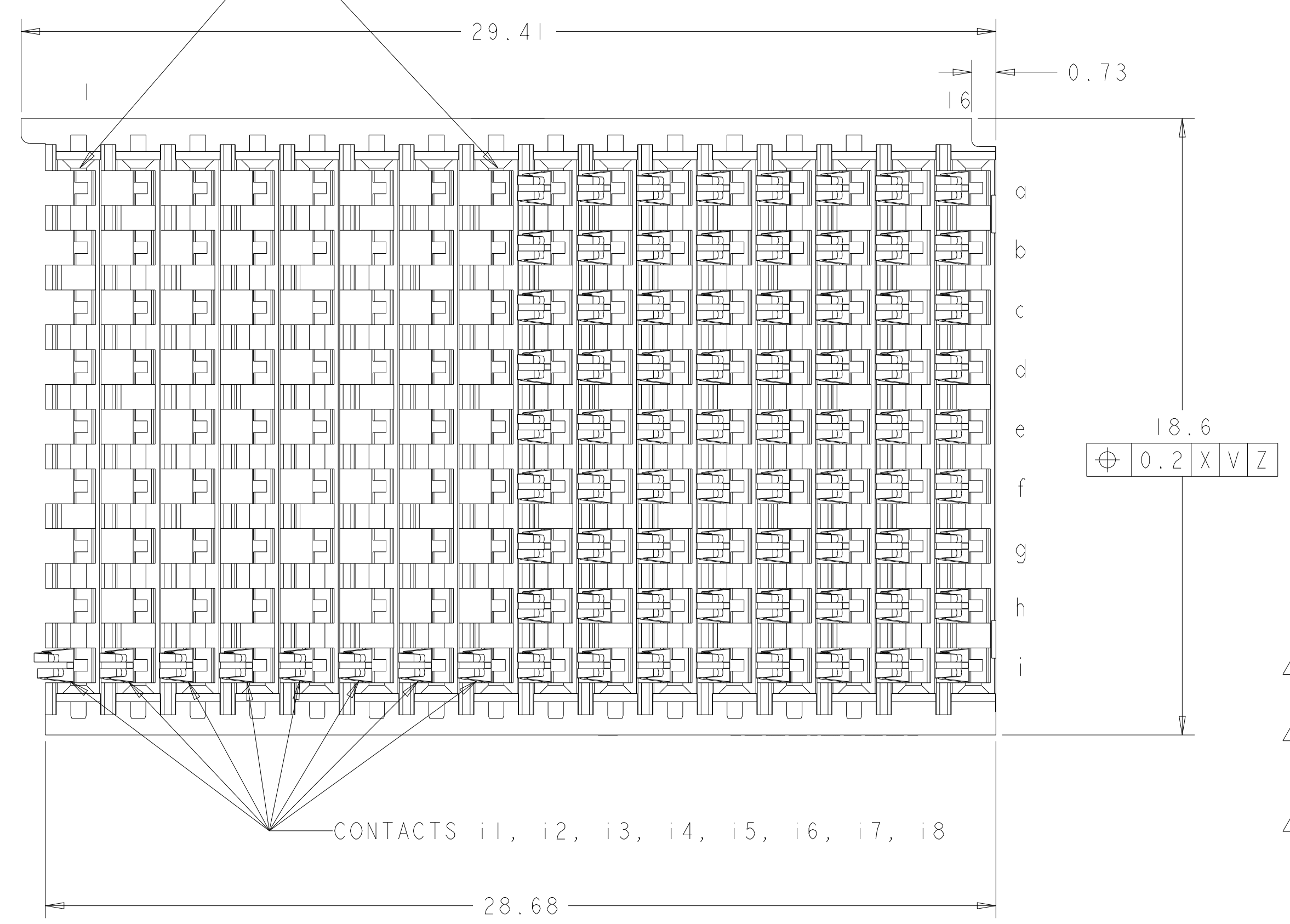
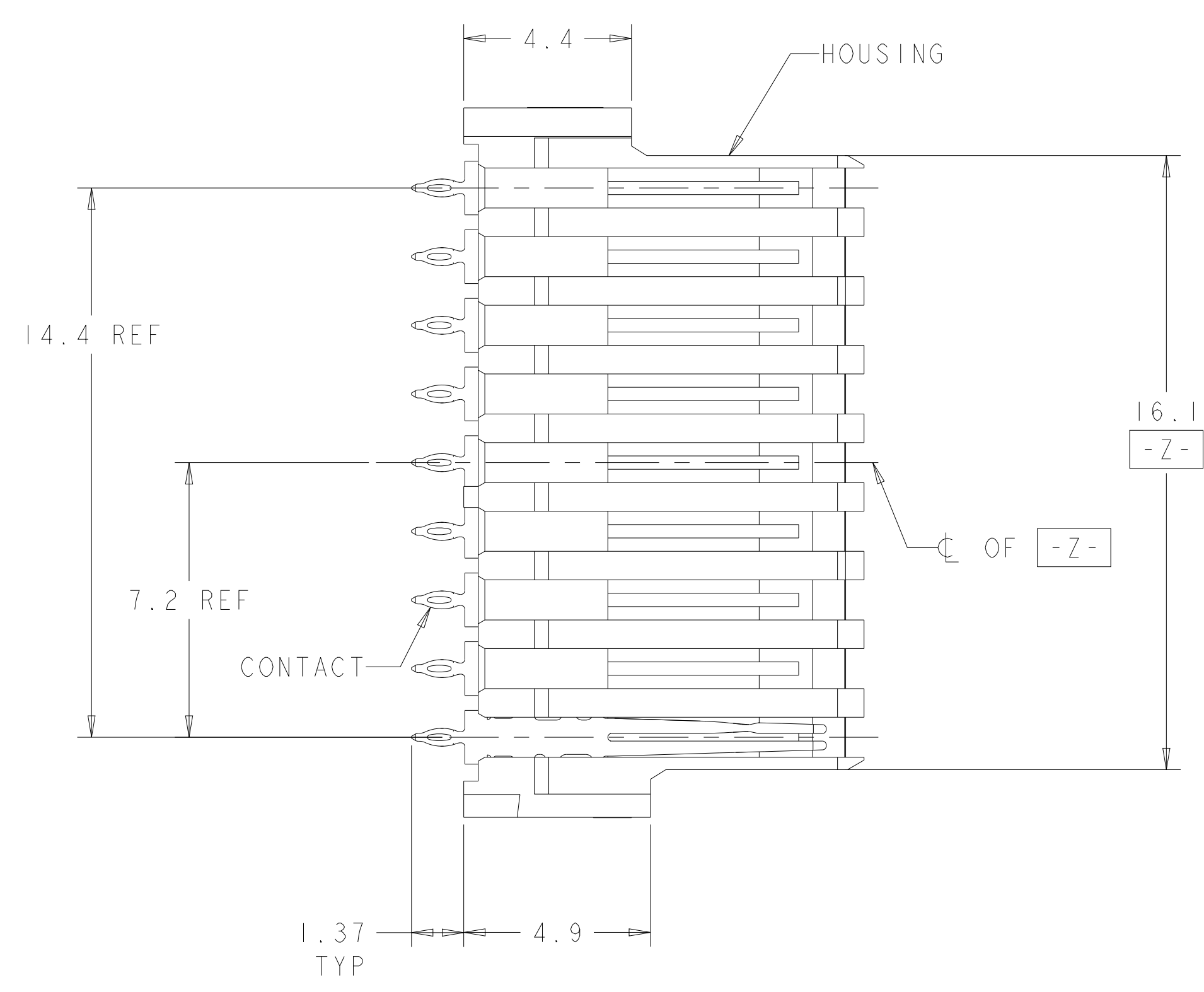
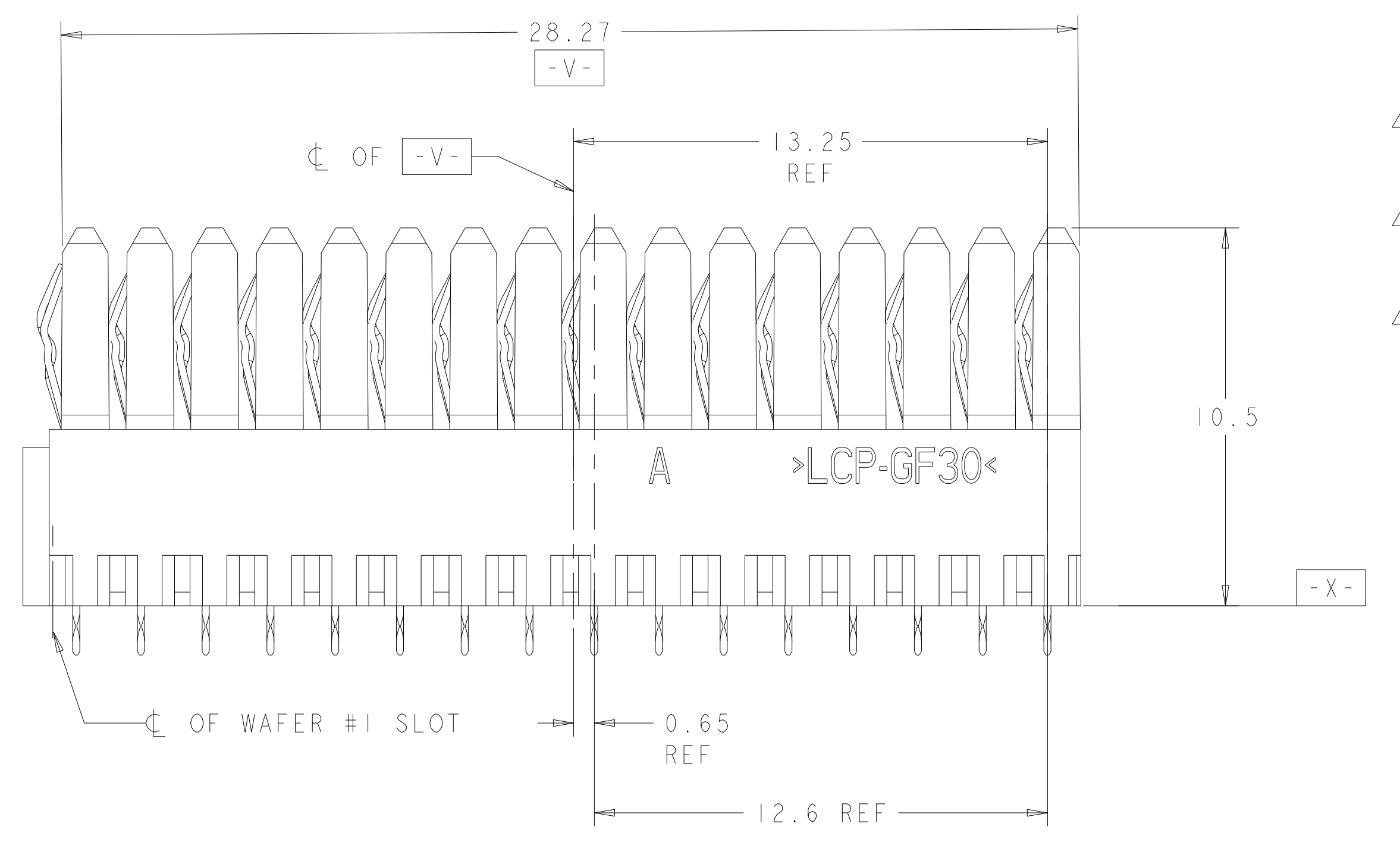
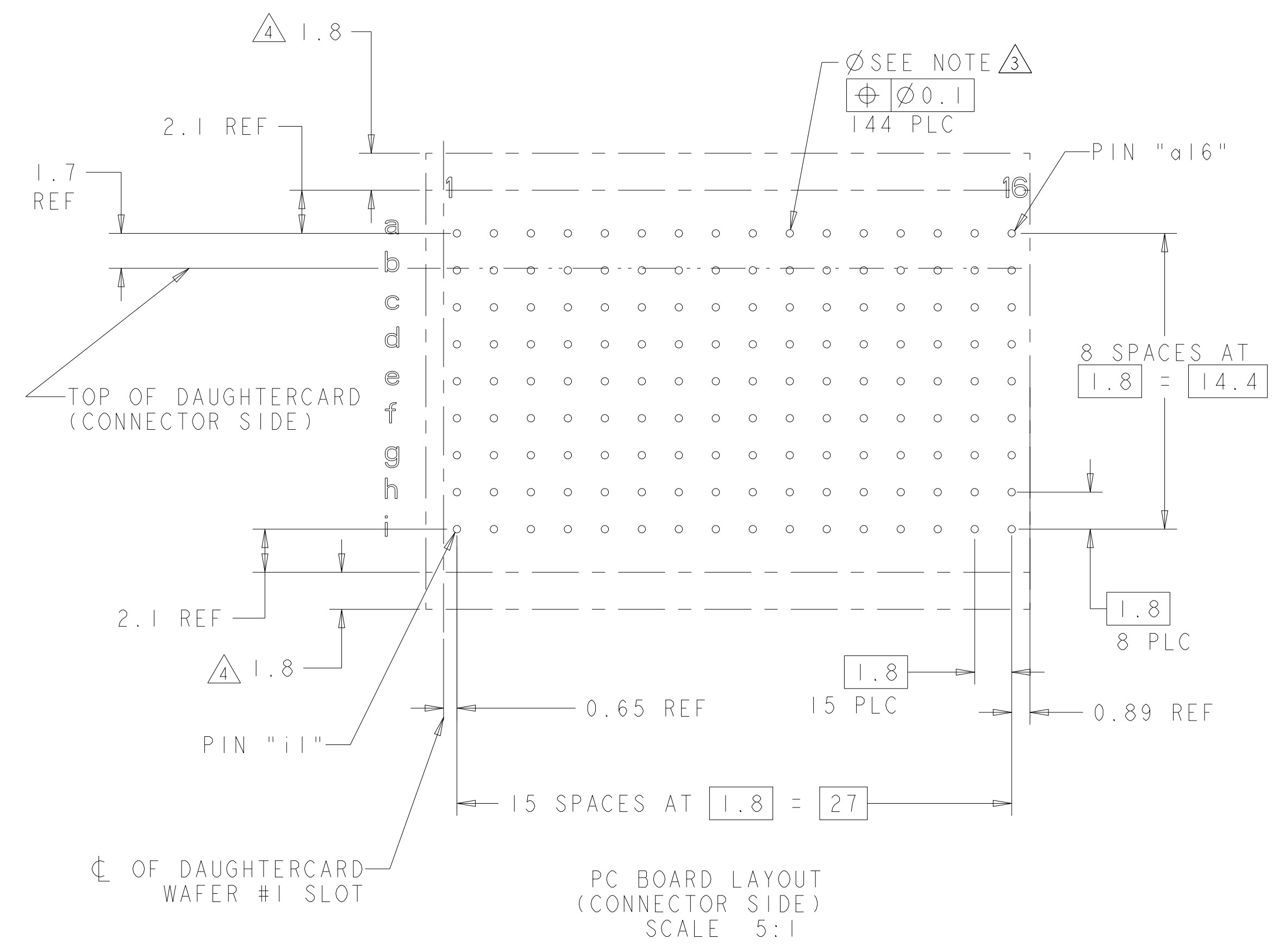


REVISIONS				
P	LTN	DESCRIPTION	DATE	APPV
A		RELEASED PER ECO-19-001811	05FEB2019	DCB AT
B		REVISED PER ECO-21-003080	28OCT2021	LN DH

COLUMNS 1 THRU 8
 CONTACTS NOT LOADED
 EXCEPT i1, i2, i3, i4, i5, i6, i7, i8



- 1 HOUSING: LCP, UL94V0, COLOR: BLACK.
CONTACT: PHOSPHOR BRONZE.
- 2 FINISH: 1.27µm GOLD IN CONTACT AREA 1.27µm MIN. TIN-LEAD (93/7) ON PCB TAIL OVER 2.54µm MIN. NICKEL OVER ALL.
- 3 PLATED THRU HOLE SPECIFICATION:
 -DRILLED HOLE: $\varnothing 0.45 \pm 0.02$
 -0.025-0.050 THICK COPPER PLATING (MAX HARDNESS 150 KNOOP)
 FINISH OPTIONS:
 -0.0038-0.0124 HOT AIR SOLDER LEVELING (HASL) TIN-LEAD (SnPb)
 -0.0005-0.004 IMMERSION TIN (Sn)
 -0.0002-0.0005 ORGANIC SOLDERABILITY PRESERVATIVE (OSP)
 -0.0001-0.0005 IMMERSION SILVER (Ag)
 -0.0001-0.0005 IMMERSION GOLD OVER 0.00127-0.0076 NICKEL (ENIG)
 FINISH HOLE DIAMETER AFTER PLATING = $\varnothing 0.36$ REF
- 4 ADDITIONAL CONNECTOR-SIDE KEEP-OUT AREA REQUIRED IF CONNECTOR-SIDE EXTRACTION TOOL IS TO BE USED.
- 5 FINISH: 1.27µm MIN GOLD IN CONTACT AREA, 0.50µm MIN TIN ON PCB TAIL OVER 2.54µm MIN. NICKEL OVER ALL.
- 6 FINISH: 1.27µm GOLD IN CONTACT AREA 1.27µm MIN. TIN-LEAD (60/40) ON PCB TAIL OVER 2.54µm MIN. NICKEL OVER ALL.



1	2302793-3
6	2302793-2
2	2302793-1
PLATING	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	OWN: A. MILLER 11JUL2017	CHK: A. TSANG 11JUL2017	APVD: A. TSANG 11JUL2017
mm	0 PLC ±0.5 1 PLC ±0.5 2 PLC ±0.13 3 PLC ±0.13 4 PLC ±0.13 ANGLES ±1°	NAME: VERTICAL RECEPTACLE ASSEMBLY, CENTER, SELECT LOAD, RTM MULTIGIG RT 3	PRODUCT SPEC: 108-2072-3	APPLICATION SPEC: 114-163004
MATERIAL:	FINISH: SEE TABLE	SIZE: 114-163004	WEIGHT: 5.35g	RESTRICTED TO: RESTRICTED CUSTOMER

TE Connectivity

SCALE 8:1 SHEET 1 OF 1 REV B